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SOLDER SUPPLYING METHOD

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INVENTOR(s): TAKEMURA SEIICHI

APPLICANT(s): NEC HOME ELECTRONICS LTD [000193] (A Japanese Company or Corporation), JP (Japan)

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#### ABSTRACT

PURPOSE: To ensure the supply of solder, by forming the solder layer at one side of long tape of heat-proof, pressing and running the solder layer on the plane to be soldered by taking back the solder layer, and melting a part of solder and replacing it on this plane.

CONSTITUTION: At one side of the long tape 12 of heat-proof such as polyimide and stainless steel, solder layer is coated and it is wound on the tape supply spool 13 so that the layer is placed outside. In this case, on the way of winding, the solder supplied material 16 placed on the heat block 17 is provided under the lower side of the tape 12 and the depression rod 15 consisting of punch is provided at the upper side. After this, the tape 12 is fed intermittently, and the solder layer is pressed on the member 16 with the depression rod 15 while temporary stopping. Since the member 16 is heated with the heat block 17, the solder layer is molten and it moves on the surface of the member 16 apart from the tape 12.